7	Lauer	Name	Material	Thickness	Constant	intan	omnet-intan	intan-drive
-		Fotolack	Solder Resist		9.51			
~		Top Layer	Copper	0.012mm				
က		Dielectric 1	FR-4	0.022mm	4.2			
4		Adhesive 1		0.025mm	4.2			
IO.		GND	Copper	0.012mm				
<b>v</b>		Adhesive 2		0.025mm	4.2			
~		Dielectric 2	FR-4	0.022mm	4.2			
00		Bottom layer	Copper	0.012mm				
တ		Bottom Solder	Solder Resist		, 10 10			

Layer	r Name	Material	Thickness	Constant	intan	omnet-intan	intan-drive
-	Fotolack	Solder Resist		3.5			
7	Top Layer	Copper	0.012mm				
က	Dielectric 1	FR-4	0.022mm	4.2			
+	Adhesive 1		0.025mm	4.2			
ເດ	QNS	Copper	0.012mm				
<b>v</b>	Adhesive 2		0.025mm	4.2			
~	Dielectric 2	FR-4	0.022mm	4.2			
<b>©</b>	Bottom layer	Copper	0.012mm				
တ	Bottom Solder	Solder Resist		წ			

Lauer	Name	Material	Thickness	Constant	intan	omnet-intan	intan-drive
-		Solder Resist		3.5			
7	Top Layer	Copper	0.012mm				
m	Dielectric 1	FR-4	0.022mm	4.2			
+	Adhesive 1		0.025mm	4.2			
ហេ	GND	Copper	0.012mm				
v	Adhesive 2		0.025mm	4.2			
N	Dielectric 2	FR-4	0.022mm	4.2			
œ	Bottom layer	Copper	0.012mm				
ຓ	Bottom Solder	Solder Resist		3.5			